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MDT0700AC-USBC	1920 x 1200	USB-C Interface	TFT Module						
	Specification								
Version: 1	Version: 1 Date: 22/04/2023								
		Revision							
1	20/04/2023	First issue							

Display I	eatures		
Display Size	7.00"		
Resolution	1920 x 1200		
Orientation	Portrait		1
Appearance	RGB		SIL
Supply Voltage	5V		OMPliant
Interface	USB-C	CC	mnliant
Brightness	410 cd/m ²		mphant
Touchscreen	CTP	5	
Module Size	108.70 x 165.80 x 15.51 ^{MAX} mm	Created By	Checked By
Operating Temperature	-20°C ~ +70°C	CL	WE
Pinout	N/A	Box Quantity	Weight / Display
Pitch	N/A		

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Display Accessories				
Part Number	Description			

Optional Variants					
Appearances	Voltage				

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1. Basic Specifications

* Description

This is a plug and play device, this is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit, capacitance touch panel, back-light unit, HDMI adapter board. The resolution of a 7.0" TFT-LCD contains 1920x1200 pixels, and can display up to 16.7M colors.

* Operating Instructions

This product supports the following operating systems: Windows 8/10/11, Android, Linux, etc.

- 1.Connect the type c connector.
- 2. Connect the typec c cable to Windows 8/10/11 or Android or Linux, etc.

1.1 TFT Features

i catures				
General Information	Specification	l lni4	Note	
Items	Main Panel	Unit	Note	
Display area(AA)	151.20(H) *94.50(V) (7.0 inch)	mm		
Driver element	TFT active matrix			
Display colors	16.7M	colors		
Number of pixels	1200(RGB)*1920	dots		
Pixel arrangement	RGB vertical stripe	<u> </u>		
Pixel pitch	0.07875 (H) x 0.07875 (V)	mm		
Viewing angle	Free	o'clock		
Display mode	Transmissive /Normally Black	SUPP	LY	
Module bonding technology	Use Optical bonding between LCM and CTP	-		
Operating temperature	-20~+70	$^{\circ}\!$		
Storage temperature	-30∼+80	$^{\circ}\! \mathbb{C}$		

1.2 Module Features

General Information Items	Specification	Unit	Note
Display Interface	Type C	-	
Touch Interface	Type C	-	
Touch Type	Capacitive touch panel	-	
Touch Mode	Multiple point	-	
Power supply	Type C	-	

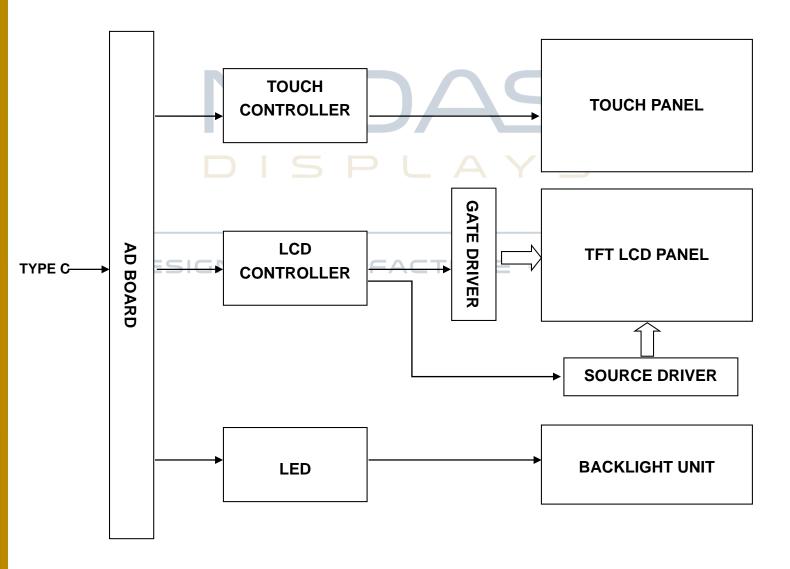
Note: Video and touch and power are transfered by type c cable.

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1.3 Mechanical Information

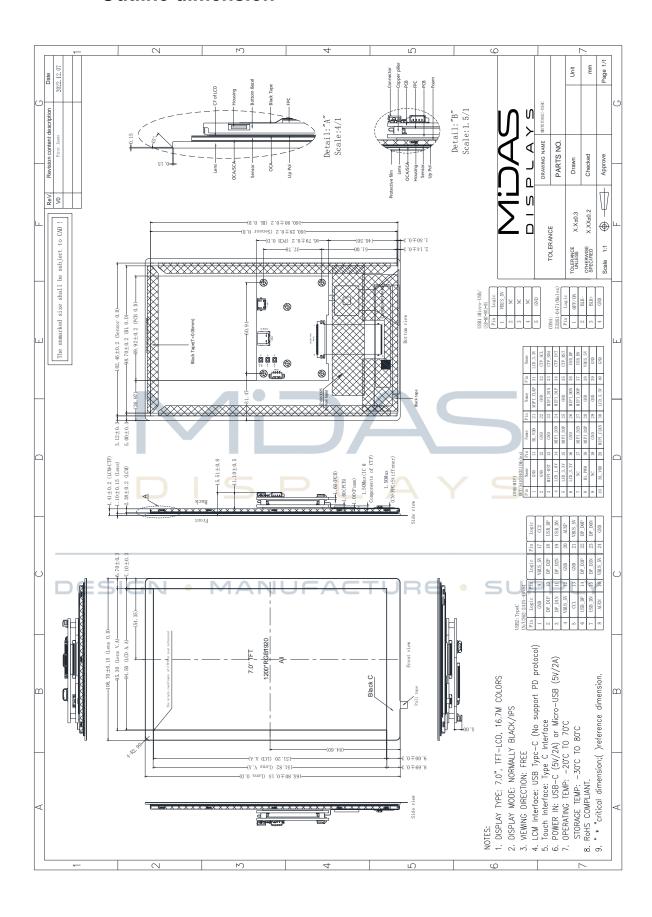
Item		Min.	Тур.	Max.	Unit	Note
Module size	Horizontal(H)	-	108.7	-	mm	
	Vertical(V)	-	165.80	-	mm	
	Depth(D)	-	-	15.51	mm	
Weight		-	TBD	-	g	

2. Block Diagram



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3. Outline dimension



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4. Pin Assignment

4.1 Type C Input

NO.	SYMBOL	DESCRIPTION	I/O
A1	GND	Ground.	Р
A2	SSTXP1	Positive TX Super Speed Differential Signal #1.	I
А3	SSTXN1	Negative TX Super Speed Differential Signal #1.	I
A4	VBUS	Supply voltage(5V).	Р
A5	CC1	Configuration channel.	I
A6	DP1	USB2.0+ signal.	I
A7	DN1	USB2.0- signal.	I
A8	SBU1	Sideband use (SBU)	I
A9	VBUS	Supply voltage(5V).	Р
A10	SSRXN2	Negative RX Super Speed Differential Signal #2.	I
A11	SSRXP2	Positive RX Super Speed Differential Signal #2.	I
A12	GND	Ground.	Р
B1	GND	Ground.	Р
B2	SSTXP2	Positive TX Super Speed Differential Signal #2.	I
В3	SSTXN2	Negative TX Super Speed Differential Signal #2.	I
B4	VBUS	Supply voltage(5V).	Р
B5	CC2	Configuration channel.	I
B6	DP2	USB2.0+ signal.	I
B7	DN2	USB2.0- signal.	I
B8	SBU2	Sideband use (SBU)	1
В9	VBUS	Supply voltage(5V).	I
B10	SSRXN1	Negative RX Super Speed Differential Signal #1.	Р
B11	SSRXP1	Positive RX Super Speed Differential Signal #1.	Р

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B12	GND	Ground.	Р	
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4.2 Backup power Input

USB1(Micro USB)

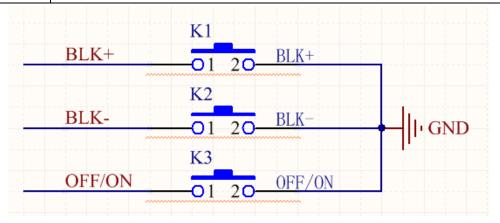
NO.	SYMBOL	DESCRIPTION	I/O
1	VBUS_5V	Supply voltage(5V).	Р
2	NC	No connection.	
3	NC	No connection.	
4	NC	No connection.	
5	GND	Ground.	Р

Note: When the power of type c is not enough, user could enable this power, usually user don't need to enable it.

4.3 Backlight Key Input

CON4(Molex: 53261-0471)

NO.	SYMBOL	DESCRIPTION	I/O
1	OFF/ON	Turn off or turn on backlight.	I
2	BLK-	Reduce brightness of backlight.	I
3	BLK± SI	Increase brightness of backlight. Note: The brightness is configured for maximum after power on.	I
4	GND	Ground	Р



key circuit diagram

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5. LCM Optical Characteristics

5.1 Optical specification

Item		Symbol	Condition	Min.	Тур.	Max.	Unit.	Note
Contrast Ra	atio	CR		800	1100			(1)(2)
	Rising				25	35		
Response time	Falling	$T_{R+}T_{F}$			70		msec	(1)(3)
Color Gam	nut	S(%)		-0.02	0.2952	+0.02	%	
LCM Lumina	ınce	LV		350	410		cd/m2	
		Wx	Θ=0		25			(1)(4)
	White	W _Y	Normal viewing		0.3366	35		CF
	Red	R _X	angle		0.6492			glass
Color Filter		Ry	•		0.3474			
Chromacicity	Green	Gx	1) /	0.04	0.2926	. 0. 0.4		
		GY		-0.04	0.6010	+0.04		
		Bx	5 P L	A	0.1490			
	Blue	By			0.0856			
		ΘL		75	80			(1)(4)
Viewing angle	Hor.	ΘR		75	80			
	SIGN	ΘU	AN CR>10ACT	URE 75	80	PPU	Y	
	Ver.	ΘD		75	80			
Option View Di	rection		Free					

^{*}The data comes from the LCD specification.

Measuring Condition

Measuring surrounding : dark room Ambient temperature : 25±2_°C

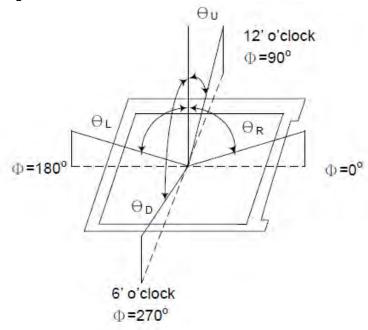
15min. warm-up time.

Measuring Equipment

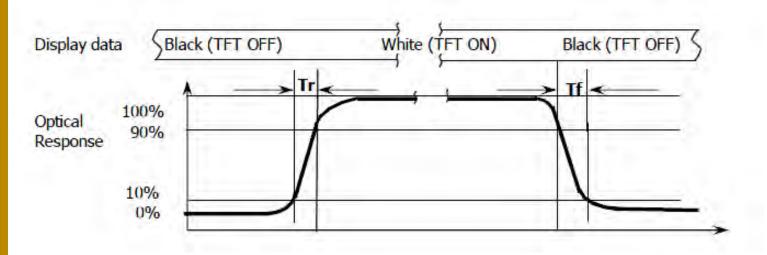
FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

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Note (1): Definition of Viewing Angle:

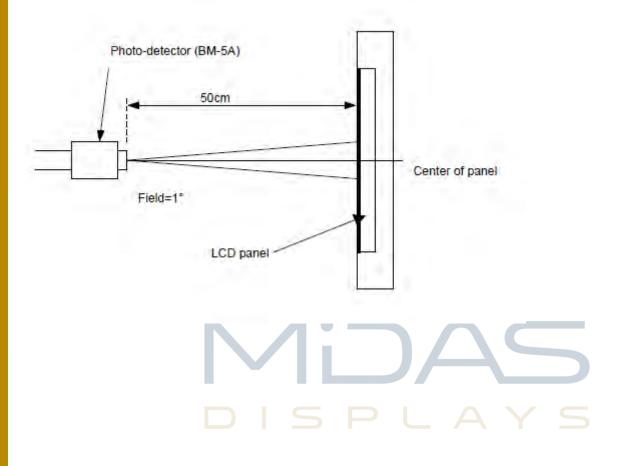


Note (2): Definition of Contrast Ratio(CR) :measured at the center point of panel



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Note (4): Definition of optical measurement setup



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6. Electrical Characteristics

6.1 Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VBUS	-0.5	6	V	Note1
Operating temperature	T _{OP}	-20	+70	°C	
Storage temperature	T _{ST}	-30	+80	°C	

NOTE1: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

6.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Power Supply Voltage	VBUS	4.5	5	5.5	V	
Normal mode Current consumption	IvBus		300		mA	

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7. LCM Module Out-Going Quality Level

7.1 VISUAL & FUNCTION INSPECTION STANDARD

7.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

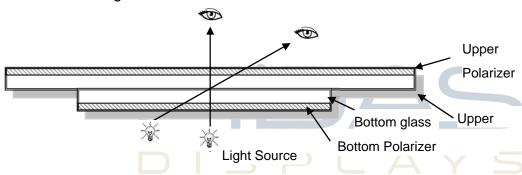
Temperature : 25±5°C

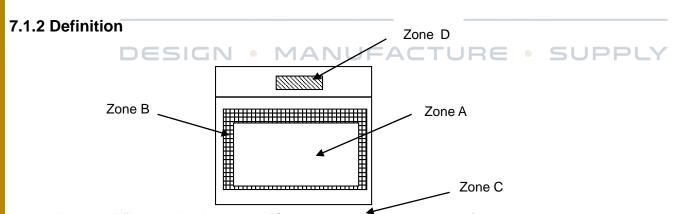
Humidity: 65%±10%RH

Viewing Angle: Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm





Zone A: Effective Viewing Area(Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A+Zone B) which can not be seen after assembly by customer.)

Zone D: IC Bonding Area

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

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7.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class $\,$ II AQL:

Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display, LCM: Liquid Crystal Module, CTP: Capacitive Touch Panel

No	Items to be inspected	Criteria	Classification of defects
		1) No display, Open or miss line	
1	Functional defects	2) Display abnormally, Short	
'	Functional defects	3) Backlight no lighting, abnormal lighting.	
		etc	Major
2	Missing	Missing components and etc	
_		Overall outline dimension beyond the drawing	
3	Outline dimension	is not allowed, deformation and etc	
4	Color tone	Color unevenness, refer to limited sample	
		Light dot,Dim spot,(Note1)	
5	Spot/Line defect	Polarizer Air Bubble,	
		Polarizer accidented spot and etc	Minor
6	Soldering appearance	Good soldering , Peeling off is not allowed and etc	JPPLY
7	LCD/Polarizer/CTP	Black/White spot/line, scratch, crack, etc.	

Note1: a) Light dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.

b) Dim dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.

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7.1.4 Criteria (Visual)

Number	Items	Criteria(mm)		
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height	(1) The edge of LCD broken			
L: Length of ITO,		X Y Z		
T: Height of LCD		≤3.0mm <inner border="" line="" of="" seal="" td="" the="" ≤t<=""></inner>		
	(2)LCD corner broken	X Y Z ≤3.0mm ≤L ≤T		
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	(3) LCD crack	Crack Not allowed		

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	Spot defect	① light dot (blac	k/white spot , pinhole, st	ain, etc.)	
	<u> </u>	Zone	Accepta	able Qty	
		Size (mm)	A	В	С
	★ Y	Ф≤0.15	Ignore		
2.0	\downarrow χ	0.15<Φ≤0.25	3(distance ≥ 10mm)		nore
2.0	^	0.25<Φ≤0.4	2(distance ≥ 10mm)		liole
	Ф=(X+Y)/2	Ф>0.4	0		
	Ψ=(/(11//2	② Dim spot (light l	eakage、dent、dark sp	ot, etc)	
		Zone	Accepta	able Qty	1
		Size (mm)	Α	В	С
		Ф≤0.15	Ignore		
		0.15<Φ≤0.25	3(distance ≥ 10mm)		gnore
		0.25<Φ≤0.4	2(distance ≥ 10mm)	-	•
		Φ>0.4 ③ Polarizer accider	oted spot		
				able Qty	
		Zone	A	В	С
		Size (mm) Ф≤0.2	1		0
			Ignore	n ma)	1
		0.2<Φ≤0.5	2(distance ≥ 10r	nm)	Ignore
		Ф>0.5	0		
		4 Polarizer Bubble			
	DESIGN •	Zone	CIURE Accept	able Qty	
		Size (mm)	A B		С
		Ф≤0.2	Ignore		
		0.2<Φ≤0.4	2(distance ≥ 10mm	1)	Ignore
		Ф>0.4	0		

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3.0	LCD Pixel defect	Pixel bad poi	nts	
		Item	Zone A	Acceptable Qty
			Random	N≤2
		Bright dot	2 dots adjacent	N≤0
			3 dots adjacent	N≤0
			Random	N≤3
		Dark dot	2 dots adjacent	N≤0
			3 dots adjacent	N≤0
		Distance	 Minimum Distance Between Bright dots. Minimum Distance Between dark dots Minimum Distance Between dark and bright dot. 	5mm
		Total bright and dark dot		N≤4
		LCD pane	: Dots appear bright and unchanged is displaying under black pattern. Dots appear dark and unchanged in	
	DESIGN	panel is d	isplaying under pure red, green, blue	e picture.
		C) 2 dot adja Picture:	cent = 1 pair = 2 dots	
		2 dot adja	cent 2 dot adjacent	
		2 dot adjacer	nt (vertical) 2 dot adjacent (slant)

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	Line defect (LCD /Polarizer backlight	VAC althe (see see)	Length(m	Acce	ptable Q	ty
	black/white line,	Width(mm)	m)	А	В	С
4.0	scratch, stain)	Ф≤0.05	Ignore	Ignore	;	
4.0		0.05 <w≤0.06< td=""><td>L≤5.0</td><td>N≤3</td><td></td><td>Ignore</td></w≤0.06<>	L≤5.0	N≤3		Ignore
	W: width, L∶ length	0.06 <w≤0.08< td=""><td>L≤4.0</td><td>N≤2</td><td></td><td></td></w≤0.08<>	L≤4.0	N≤2		
	N : Count	W>0.08		Define as spo	t defect	
	Electronic Componen					
	Licetionic Componen	•				der joint, m
5.0	ts SMT.	match, The positive a				der joint, m
5.0	·	•	the color coole datasheet o	rdinates, The r samples.	measure	ment standa

	СТР		<u> </u>		, o i i c	
	Related	CTP Cover	Size Ф(mm)	Д	cceptable Qty	•
		sensor	Oize $\Phi(iiiii)$	Α	В	С
		accidented	Ф≤0.15	Ign	ore	
8.0		black/white	0.15<Φ≤0.25	4 (distance	e≧10mm)	Ignore
0.0		spot	0.25<Φ≤0.35	3 (distance	e≧10mm)	
			Φ>0.35	()	

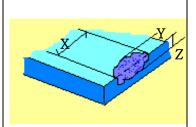
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			Ignore(Acc	eptable Qty	
		Width(mm)	mm)	Α	ВС	
	CTP Cover	Ф≤0.05	Ignore		Ignore	
	scratch	0.05 <w≤0.06< td=""><td>L≤4.0</td><td></td><td>N≤3</td><td></td></w≤0.06<>	L≤4.0		N≤3	
		0.06 <w≤0.08< td=""><td>L≤3.0</td><td></td><td>N≤2</td><td></td></w≤0.08<>	L≤3.0		N≤2	
		0.08 <w< td=""><td>De</td><td>fine as sp</td><td>ot defect</td><td></td></w<>	De	fine as sp	ot defect	
		Zone		Acceptal	ole Qty	
	CTP Cover	Size (mm)		С		
	Pinhole/	Φ≤0.2		Igno	re	
	Lack of ink	0.2<Φ≤0.3	4	l(distance		
	2001 01 1111	0.3<Φ≤0.4	2	2(distance	≧10mm)	
		Ф>0.4		0		
	7.					
	OTD			Acceptabl	e Otv	
	CTP	Size Φ(mm)	А	/ locoptabl	B	
	Bonding	Ф≤0.1		Ignore	В	
	bubble/ accidented	0.1<Φ≤0.2	3(c	distance≧	10mm)	
	spot	0.2<Φ≤0.3		distance≧		
	Зрог	Ф>0.3		0		
DESIGN	Assembly deflection	DEACTURE beyond the edge of	backlight ≤0.	SUPF .2mm	PLY	
	CTP cover	X Y	Z	1		
	broken	1	Z <cover< td=""><td>X></td><td>Y</td><td></td></cover<>	X>	Y	
	X : length	X≤0.5mm Y≤0.5mn				
	Y: width	7.20.011111	S			
	Z : height	Circuitry broken is	•		~	

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	CTP cover
	broken
	X: length
	Y: width
	7 : height

X	Y	Z	
		Z <cover< td=""></cover<>	
X≤0.3mm	Y≤0.3mm	thicknes	
		S	



* Circuitry broken is not allowed.

Criteria (functional items)

Number	Itomo	Criteria (mm)
Number	Items No display Missing segment Short Backlight no lighting CTP no function	Not allowed
1		Not allowed
2		Not allowed
3		Not allowed
4		
5		

DISPLAYS

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8. Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	70°C,96HR	
Low Temperature Operating	-20℃, 96HR	
High Temperature Storage	80°C, 96HR	
Low Temperature Storage	-30°C, 96HR	Inspection after 2~4hours
High Temperature & High	+60°C, 90% RH ,96 hours.	storage at room temperature, the sample shall be free from
Humidity Operating	-,,,,,,,,,,	defects:
Thermal Shock (Non-operation)	-30°C,30 min ↔ 80°C,30 min,	1.Air bubble in the LCD;
	Change time:5min 20CYC.	2.Non-display;
ESD test	C=150pF, R=330,5points/panel	3.Missing segments/line;
	Air:±8KV, 5times; Contact:±6KV, 5 times;	4.Glass crack;
	(Environment: 15°C~35°C, 30%~60%).	5.Current IDD is twice higher
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm	than initial value.
	Sweep:10Hz~55Hz~10Hz 2 hours for each direction of	
	X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

Remark:

- 1. The test samples should be applied to only one test item.
- 2. Sample size for each test item is 3~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance $> 10M\Omega$) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

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9. Cautions and Handling Precautions

9.1 Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
- Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.
- If you have the droplets for a long time, staining and discoloration may occur.
- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
- Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.

9.2 Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
- It is highly recommended to store the module with temperature from 0 to 35 $\,^\circ\mathbb{C}\,$ and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
- In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

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